



PK732 (v1.0) May 29, 2015

# 100% Material Declaration Data Sheet Spartan®-6 Cu Wire FG676 Package

**Average Weight: 3.1467 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.090946</b>	<b>4.125%</b>
	Silicon	7440-21-3	100.00	Main material	0.090946	
<b>Die Attach Material</b>					<b>0.016016</b>	<b>1.245%</b>
	Silver	7440-22-4	77.50	Main material	0.012412	
	Bismaleimide monomer	Trade Secret	15.00	Main material	0.002402	
	Acrylate monomer	Trade Secret	7.50	Main material	0.001201	
<b>Copper Wire</b>					<b>0.005681</b>	<b>0.305%</b>
	Cu	7440-50-8	98.25	Main material	0.005582	
	Pd	7440-05-3	1.75	Dopant	0.000099	
<b>Mold Compound</b>					<b>1.373571</b>	<b>34.945%</b>
	Epoxy Resin	Trade secret	3.00	Main material	0.041207	
	Phenol Resin A	9003-35-4	3.00	Main material	0.041207	
	Phenol Resin B	Trade secret	3.00	Main material	0.041207	
	Silica(Amorphous) A	60676-86-0	72.45	Filler	0.995152	
	Silica(Amorphous) B	7631-86-9	15.00	Filler	0.206036	
	Metal Hydroxide	Trade secret	3.00	Flame retardant	0.041207	
	Carbon black	1333-86-4	0.55	Color agent	0.007555	
<b>Solder Balls</b>					<b>0.643415</b>	<b>13.264%</b>
	Tin (Sn)	7440-31-5	63.00	Main material	0.405351	
	Lead (Pb)	7439-92-1	37.00	Main material	0.238064	

© Copyright 2015 Xilinx, Inc. XILINX, the Xilinx logo, Virtex, Spartan, ISE, and other designated brands included herein are trademarks of Xilinx in the United States and other countries. All other trademarks are the property of their respective owners

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Substrate</b>					<b>1.017079</b>	<b>46.116%</b>
	Au	7440-57-5	0.808	Main material	0.008223	
	Ni	7440-02-0	7.849	Main material	0.079830	
	Cu foil	7440-50-8	8.010	Main material	0.081472	
	Cu plating	7440-50-8	18.124	Plating	0.184331	
	Continuous Filament Fiber Glass	65997-17-3	17.895	Glass Fiber	0.182003	
	BT Core	7440-50-8 N/A	32.636	Core	0.331938	
	Solder Mask	14807-96-6 7727-43-7 7631-86-9 34590-94-8 91-20-3 85954-11-6 N/A	10.524	Solder mask	0.107035	
	Prepregs	NA	4.154	Prepregs	0.042247	

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
5/29/15	1.0	Initial Xilinx release

## Notice of Disclaimer

Xilinx regards this materials data to be correct but makes no guarantee as to its accuracy or completeness, including, but not limited to, with respect to its compliance with applicable environmental laws and regulations. Xilinx subcontracts the production, test and assembly of hardware devices to independent third-party vendors and materials suppliers ("Contractors"). All data provided hereunder is based on information received from Contractors. Xilinx has not independently verified the accuracy or completeness of this information which is provided solely for your reference in connection with the use of Xilinx products.